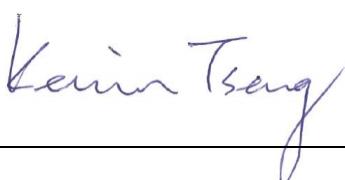


To : Dear Valued Customers

## Product/Process Change Notice

We hereby submit PCN for your review and approval.

Application or type :						
The product add new assembly site.						
Detail of the change :						
The manufacturing sites are existing qualified suppliers of Comchip.						
Reason for the change :						
This notification is to advise our customers that we will add the new assembly site of the following product to better support long-term demand for the affected products.						
Full electrical characterization and reliability testing have been completed on representative part numbers to ensure there is no change to device function or electrical specifications in the datasheet.						
Reliability reports as attached file.						
Evaluation items :						
<table border="1"><thead><tr><th>Part No.</th><th>Package Type</th></tr></thead><tbody><tr><td>TV06A5V0-HF Thru. TV06A580-HF</td><td>SMA/DO-214AC</td></tr><tr><td>MMSZ5221B-HF Thru. MMSZ5267B-HF</td><td>SOD-123</td></tr></tbody></table>	Part No.	Package Type	TV06A5V0-HF Thru. TV06A580-HF	SMA/DO-214AC	MMSZ5221B-HF Thru. MMSZ5267B-HF	SOD-123
Part No.	Package Type					
TV06A5V0-HF Thru. TV06A580-HF	SMA/DO-214AC					
MMSZ5221B-HF Thru. MMSZ5267B-HF	SOD-123					
* Subject to ROHS product material survey table final confirmation.						
Implemented from :						
Effective immediately.						
R&D Dept. Signature :	QA Dept. Signature :					
						

## **Answer To PCN**

Please complete the form below duly signed and fax back to Comchip Technology Co.

Please select your answer	Date
1. Approved this PCN 2. Approved this PCN with conditions 3. Disapproved this PCN	Responsibility By
Please specify the condition or explain the reason if you select 2 or 3.	

Unless a Comchip Technology Co., Ltd. Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.



# Reliability Test Report

**Part NO.:** Part No. affected **Diodes**

Doc. No. **PCN240502**

Date: 2024.05.02

ComChip Technology Co., Ltd.

Add. : No. 586, Jianguo Rd., Yingge Dist.,  
New Taipei City 23943, Taiwan

Tel : 886-2-8677-6675

**Reliability Test Summary**
**P / N :** Part No. affected

**Doc. No. :** PCN240502

No	Test Item	Test Condition	Test Foundation	Failure qty'	S.S	Test Results
1	Solderability	Dip in flux Time=5sec. Temp.of solder Pot=245±5°C Time= 5~10 sec.	MIL-STD-750 Method 2026	0	22	PASS
2	Soldering Heat	Temp of solder pot=260±5°C Time= 10~12 sec	MIL-STD-750 Method 2031	0	22	PASS
3	Temperature Cycle	Low Tstg to High Tstg dwelled for 30 min and transfer time not exceed 1 min; 20 cycles	MIL-STD-750 Method 1051	0	22	PASS
4	High Temperature Reverse Bias Life	VR= VR*80% Temp.(depend on product) Time 168hrs.	MIL-STD-750 Method 1038	0	22	PASS
4a (Z)	Steady State Operational	Ic =Ptmax/Vzmin Ta= 25 °C. Test Time 168hrs.	MIL-STD-750 Method 1038	0	22	PASS
5	Pressure Cooker Test	Ta= 121°C Pressure= 15 Psi Time= 4 hrs	JESD 22-A102	0	22	PASS
6	High Temperature Storage Life	Ta= High Tstg. Time= 168 hrs	MIL-STD-750 Method 1031	0	22	PASS
7	Humidity	Ta= 85 °C RH= 85% Time=168 hrs	EIAJ ED-4701	0	22	PASS

Conclusion:

1. The total test had 7 item of reability test.
2. There were test result of pass.
3. (Z) Required for Zener parts only.

Approval: Zeus Lai

Prepare: Judy Lin